# ne<mark>x</mark>peria

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Should be replaced with:

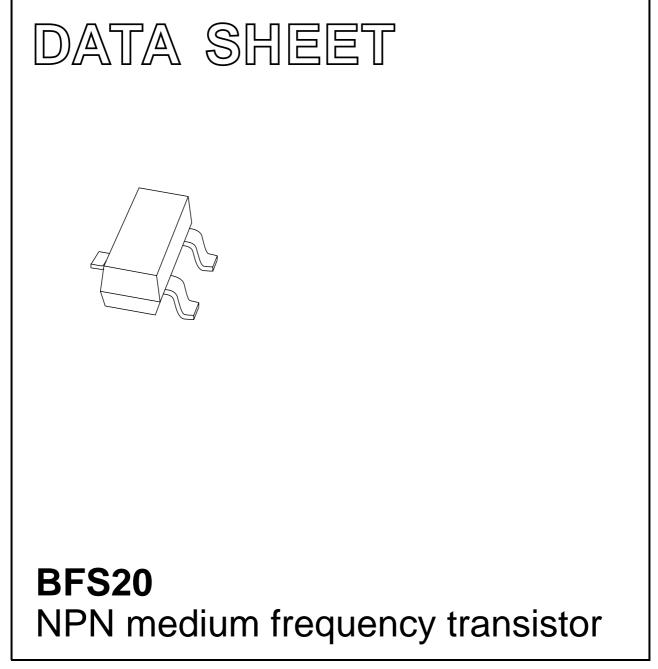
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Kind regards,

Team Nexperia

### DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2004 Jan 5 2004 Feb 05



### FEATURES

- I<sub>C(max)</sub> = 25 mA
- V<sub>CEO(max)</sub> = 20 V
- Very low feedback capacitance (typ. 350 fF).

### APPLICATIONS

• IF and VHF thick and thin-film circuit applications.

### DESCRIPTION

NPN medium frequency transistor in a SOT23 plastic package.

### MARKING

| TYPE NUMBER | MARKING CODE <sup>(1)</sup> |  |  |
|-------------|-----------------------------|--|--|
| BFS20       | G1*                         |  |  |

#### Note

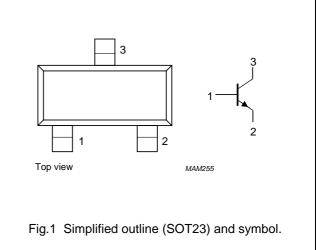
- 1. \* = p : Made in Hong Kong.
  - \* = t : Made in Malaysia.

\* = W : Made in China.

### **ORDERING INFORMATION**

| PINNING |
|---------|
|         |

| PIN | DESCRIPTION |  |
|-----|-------------|--|
| 1   | base        |  |
| 2   | emitter     |  |
| 3   | collector   |  |



| TYPE   | PACKAGE |  |       |  |  |
|--------|---------|--|-------|--|--|
| NUMBER | NAME    | DESCRIPTION VERSION                      |       |  |  |
| BFS20  | _       | plastic surface mounted package; 3 leads | SOT23 |  |  |

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL           | PARAMETER                     | CONDITIONS                            | MIN. | MAX. | UNIT |
|------------------|-------------------------------|---------------------------------------|------|------|------|
| V <sub>CBO</sub> | collector-base voltage        | open emitter                          | -    | 30   | V    |
| V <sub>CEO</sub> | collector-emitter voltage     | open base                             | -    | 20   | V    |
| V <sub>EBO</sub> | emitter-base voltage          | open collector                        | -    | 4    | V    |
| I <sub>C</sub>   | collector current (DC)        |                                       | -    | 25   | mA   |
| I <sub>CM</sub>  | peak collector current        |                                       | -    | 25   | mA   |
| P <sub>tot</sub> | total power dissipation       | $T_{amb} \le 25 \ ^{\circ}C$ ; note 1 | -    | 250  | mW   |
| T <sub>stg</sub> | storage temperature           |                                       | -65  | +150 | °C   |
| Tj               | junction temperature          |                                       | _    | 150  | °C   |
| T <sub>amb</sub> | operating ambient temperature |                                       | -65  | +150 | °C   |

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

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### THERMAL CHARACTERISTICS

| SYMBOL               | PARAMETER                                   | CONDITIONS | VALUE | UNIT |  |
|----------------------|---|------------|-------|------|--|
| R <sub>th(j-a)</sub> | thermal resistance from junction to ambient | note 1     | 500   | K/W  |  |

### Note

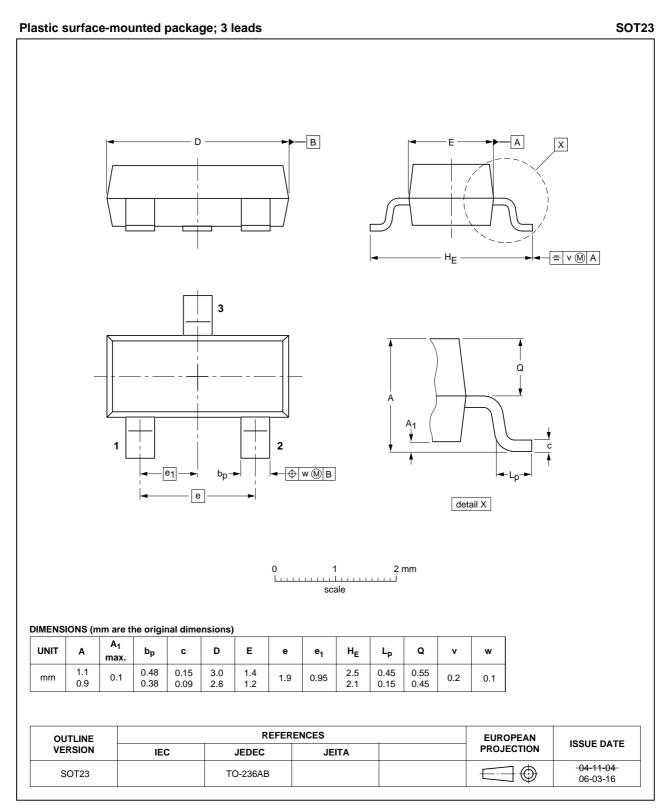
1. Transistor mounted on an FR4 printed-circuit board.

### CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

| SYMBOL           | PARAMETER                      | CONDITIONS   | MIN. | TYP. | MAX. | UNIT |
|------------------|--------------------------------|--|------|------|------|------|
| I <sub>CBO</sub> | collector-base cut-off current | I <sub>E</sub> = 0; V <sub>CB</sub> = 20 V                             | -    | -    | 100  | nA   |
|                  |                                | I <sub>E</sub> = 0; V <sub>CB</sub> = 20 V; T <sub>j</sub> = 100 °C    | -    | -    | 10   | μA   |
| I <sub>EBO</sub> | emitter-base cut-off current   | $I_{C} = 0; V_{EB} = 4 V$  | -    | -    | 100  | nA   |
| h <sub>FE</sub>  | DC current gain                | I <sub>C</sub> = 7 mA; V <sub>CE</sub> = 10 V                          | 40   | 85   | -    |      |
| V <sub>BE</sub>  | base-emitter voltage           | I <sub>C</sub> = 7 mA; V <sub>CE</sub> = 10 V                          | -    | 740  | 900  | mV   |
| Cc               | collector capacitance          | I <sub>E</sub> = I <sub>e</sub> = 0; V <sub>CB</sub> = 10 V; f = 1 MHz | _    | 1    | _    | pF   |
| C <sub>re</sub>  | feedback capacitance           | I <sub>C</sub> = 0; V <sub>CB</sub> = 10 V; f = 1 MHz                  | -    | 350  | _    | fF   |
| f <sub>T</sub>   | transition frequency           | I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 10 V; f = 100 MHz             | 275  | 450  | -    | MHz  |

### PACKAGE OUTLINE



# BFS20

BFS20

### DATA SHEET STATUS

| DOCUMENT<br>STATUS <sup>(1)</sup> | PRODUCT<br>STATUS <sup>(2)</sup> | DEFINITION  |
|-----------------------------------|----------------------------------|---|
| Objective data sheet              | Development                      | This document contains data from the objective specification for product development. |
| Preliminary data sheet            | Qualification                    | This document contains data from the preliminary specification.                       |
| Product data sheet                | Production                       | This document contains the product specification.                                     |

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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